


Full Material Declaration for attached parts list

Report generated: 21 February 2025, 11:17 GMT

	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 01 May 2009 [Approved: 20 February 2025 15:41 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	3.89%	SILVER, ELEMENTAL	7440-22-4	4.49%
			Silicon	7440-21-3	95.51%
			Octanedioic acid	505-48-6	0.03%
			Rosin, polymd.	65997-05-9	0.1%
			Castor oil, hydrogenated	8001-78-3	0.15%
Die attach	Lead and Lead alloys	4.37%	SILVER, ELEMENTAL	7440-22-4	2.45%
			Tin elemental	7440-31-5	4.92%
			Elemental lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.35%
			Carbon black	1333-86-4	0.8%
			Silicon Dioxide	7631-86-9	2.5%
Encapsulation	EP (Epoxy resin)	44.78%	Phenol, polymer with formaldehyde	9003-35-4	3.7%
			ALUMINUM(III) HYDROXIDE	21645-51-2	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	6%
Leadfinish	Tin plating	0.55%	Silicon dioxide	60676-86-0	82%
			Tin	7440-31-5	100%
Leadframe	Steel and iron materials	46.41%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name
SOD-323P_HF	Diode SMD